

L Number	Hits	Search Text	DB	Time stamp
1	54	(adhesive near (vacuum or air or bubble\$2 or space\$2)) and (chip or die or device) and (semiconductor and ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 08:12
2	22	((adhesive near (vacuum or air or bubble\$2 or space\$2)) and (chip or die or device) and (semiconductor and ic)) and (@ad<19960509)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 08:26
4	3011481	"13" and (@ad<19960509)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 08:14
3	56	(adhesive near (porous or pore or air or bubble\$2 or space\$2 or opening)) and (chip or die or device) and (semiconductor and ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 08:24
5	879	(adhesive with (porous or pore or air or bubble\$2 or space\$2 or opening or thread pregnate)) and (chip or die or device) and (semiconductor and ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 09:00
6	300	((adhesive with (porous or pore or air or bubble\$2 or space\$2 or opening or thread pregnate)) and (chip or die or device) and (semiconductor and ic)) and (@ad<19960509)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 09:04
7	5	("4760440"   "4866506"   "4910581"   "4942452"   "5296738").PN.	USPAT	2003/02/24 08:32
9	14732	((adhesive or bond) with ((porous or pore or air or bubble\$2 or space\$2 or opening or thread\$2 or pregnate\$2)) and (stress or relax or vent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 09:03
10	3367	(adhesive or bond) with ((porous or pore or air or bubble\$2 or space\$2 or opening or thread\$2 or pregnate\$2) and (stress or relax or vent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 09:04
11	1940	((adhesive or bond) with ((porous or pore or air or bubble\$2 or space\$2 or opening or thread\$2 or pregnate\$2) and (stress or relax or vent))) and (@ad<19960509)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 09:04
12	544	((adhesive or bond) with ((porous or pore or air or bubble\$2 or space\$2 or opening or thread\$2 or pregnate\$2) and (stress or relax or vent))) and (@ad<19960509) and (chip or die or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 09:05